



AEROSPACE INFORMATION REPORT

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Investigation of Whisker Formation on Tin Plated Conductors

RATIONALE

This document has been determined to be out of date. Significant additional work by industry to further document the background and issues related to the formation, consequences, and possible mitigation actions of tin whiskers on electronic parts is located in GEIA-STD-0005-2, "Standard for Mitigating the Effects of Tin Whiskers in Aerospace and High Performance Electronic Systems."

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This document has been declared "Stabilized" by the SAE AE8-D Wire and Cable Committee, and will no longer be subjected to periodic reviews for currency. Users are responsible for verifying references and continued suitability of technical requirements. Refer to GEIA-STD-0005-2 for further information.

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Documents

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1. SCOPE:

This SAE Aerospace Information Report (AIR) shall be limited to general information about tin whisker formation on tin plated conductors. It summarizes the mechanisms of metal whisker formation and describes possible conclusions as related to tin plated conductors. It also provides a number of reference documents that describes research and observations of the whisker phenomena, recommendations to prevent its formation and conclusions.

The investigation by this task group of AE-8D was initiated by a request of the Naval Air Warfare Center, Indianapolis, Indiana, to determine if the phenomenon of tin whiskers is a problem in aerospace wire and cable.

1.1 Purpose:

This document provides some brief information about tin whisker formation and a list of reference documents that can provide more detailed information.

2. APPLICABLE REFERENCES:

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